

Application No.: 09884,844  
Amendment dated: March 1, 2006  
Reply to Office Action of December 1, 2005  
Attorney Docket No.: 1066us

This listing of claims will replace all prior versions and listings of claims in this application:

a.) Listing of Claims

1. (currently amended) An optoelectronic hermetic package, comprising:  
a frame defining a hermetic boundary; ~~and~~  
an electrical feedthrough assembly on the frame ~~1) providing~~ including: 1)  
electrical connections between signal wire bond areas within the hermetic boundary and electrical contact areas outside the hermetic boundary; and  
2) ground wire bond areas within the hermetic boundary that are electrically connected to each other; and  
conductive plugs extending between a top of the feedthrough assembly and the frame, the ground wire bond areas being located on a top of the conductive plugs.
2. (original) A package as claimed in claim 1, further comprising an array of leads extending from electrical contact areas away from the frame.
3. (original) A package as claimed in claim 2, wherein the leads extend laterally relative to the frame.
4. (previously presented) A package as claimed in claim 2, wherein the leads are pins that extend vertically relative to the frame.
5. (original) A package as claimed in claim 1, wherein at least some of the ground wire bond areas are located between two of the signal wire bond areas on the feedthrough assembly.
6. (original) A package as claimed in claim 1, wherein the ground wire bond areas are interdigitated with signal wire bond areas.

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7. (cancelled)
8. (cancelled)
9. (currently amended) An optoelectronic hermetic package, comprising:  
a frame defining a hermetic boundary;  
an electrical feedthrough assembly on the frame including: 1) electrical  
connections between signal wire bond areas within the hermetic boundary  
and electrical contact areas outside the hermetic boundary; and 2) ground  
wire bond areas within the hermetic boundary that are electrically  
connected to each other; and  
~~A package as claimed in claim 1, further comprising~~ conductive plugs  
extending between a top of the feedthrough assembly and a bus through  
the assembly, the ground wire bond areas being located on a top of the  
conductive plugs.
10. (new) A package as claimed in claim 9, further comprising an array of leads  
extending from electrical contact areas away from the frame.
11. (new) A package as claimed in claim 10, wherein the leads extend laterally  
relative to the frame.
12. (new) A package as claimed in claim 10, wherein the leads are pins that  
extend vertically relative to the frame.
13. (new) A package as claimed in claim 9, wherein at least some of the ground  
wire bond areas are located between two of the signal wire bond areas on the  
feedthrough assembly.
14. (new) A package as claimed in claim 9, wherein the ground wire bond areas  
are interdigitated with signal wire bond areas.